

A study on the electrical properties of fluorine doped direct-patternable SnO₂ thin films

Hyuncheol Kim, Hyung-Ho Park *

Department of Materials Science and Engineering, Yonsei University, Seoul 120-749, Republic of Korea

Available online 27 May 2011

Abstract

Direct-patternable fluorine doped SnO₂ (FTO) thin films were fabricated by a photochemical solution deposition method. The electrical properties and crystallinity of FTO thin films were slightly enhanced relative to undoped SnO₂ films and the improvement of electrical conduction was found to be due to an increase of carrier concentration. Direct-patterning of FTO thin films was performed without using photoresist or dry etching. These results suggest that a micro-patterned system can be simply fabricated at low cost, and the electrical properties of direct-patternable SnO₂ films can be improved by fluorine doping.

© 2011 Elsevier Ltd and Techna Group S.r.l. All rights reserved.

Keywords: A. Films; A. Sol–gel processes; C. Electrical conductivity; E. Electrodes

1. Introduction

Indium tin oxide (ITO) is widely used as a transparent electrode for solar cells and optoelectronic devices [1]. However, there are many disadvantages of ITO including the fact that it is rare, and may eventually be exhausted, and its instability in hydrogen plasma [2]. SnO₂ thin films have been increasingly studied years as transparent electrode materials due to the high optical transparency, high chemical durability, and low cost [3]. However, for electrical device applications, improvement of the electrical properties is absolutely required.

For the fabrication of electronic circuits, a micro-patterning process is commonly used. However, the conventional etching process is accompanied by the generation of physical defects and the resulting degradation of properties, and pollution from hazardous materials. By using photochemical solution deposition, photoresist and dry etching are not necessary, as the coated films behave like the negative photoresist. In doing so, damage and problems from etching were avoided [4].

Among the various doped SnO₂ films, fluorine doped SnO₂ (FTO) thin films are the lowest resistive materials. Normally, FTO thin films are fabricated using spray pyrolysis [5]. In this

method, in situ annealing of the film is possible during film deposition. However, fluorine does vaporize during drying or annealing fabrication steps, and the films have to be patterned after formation for device fabrication. So, in this study, we adopt a photochemical solution deposition (PSD) method for direct-patterning of the film.

In this work, the effects of fluorine on the properties of direct-patternable SnO₂ thin films prepared by PSD were investigated. Furthermore, direct-patterning of FTO thin films using a photosensitive solution and UV light exposure was performed to avoid damage from etching and to simplify the micron-scale patterning procedure.

2. Experimental

SnO₂ thin films were prepared by PSD. The tin source, solvent and fluorine source were tin chloride pentahydrate (SnCl₄·5H₂O), methanol (CH₃OH) and tin fluoride (SnF₂), respectively. SnCl₄·5H₂O was dissolved in CH₃OH to a final concentration of 0.3 M and 2-nitrobenzaldehyde (NBAL) was introduced as a photosensitive additive. SnF₂ was only slightly soluble in CH₃OH, and formed a cloudy solution. By using SnCl₄·5H₂O and SnF₂, we obtained a clear solution for FTO thin film fabrication containing various F/Sn atomic ratios of 0 to 1.2 [6]. The dissolved photosensitive solution was stirred at room temperature for 3 h. Small amounts of solution were spin-

* Corresponding author. Tel.: +82 2 21232853; fax: +82 2 3125375.

E-mail address: hhpark@yonsei.ac.kr (H.-H. Park).

coated at 2000 rpm for 20 s on Corning 1737 glass substrates. The spin-coated film was dried on a hot plate at 60 °C and the dried film was exposed to UV light of 365 nm. Then, the UV exposed film was washed by CH₃OH to remove the unexposed area. Films were then dried at 150 °C for 10 min and annealed at 500 °C for 1 h in a tubular furnace under a N₂ atmosphere [7]. Thicknesses of the films were obtained using scanning electron microscopy (SEM, Hitachi Model S-4200). Crystallinity was analyzed by using an X-ray diffractometer (XRD, D/MAX-2000, Rigaku) with Cu K α radiation. The electrical properties of the film were measured using Hall Effect measurements (HMS-3000, Ecopia). Optical transmittance measurements were carried out using a UV–VIS–NIR spectrophotometer (V-570, Jasco). To investigate the surface chemical bonding state, X-ray photoelectron spectroscopy (XPS, ESCALAB 220i-XL, VG Scientific) was used with an Al K α source.

3. Results and discussion

Fig. 1 provides XRD patterns of SnO₂ thin films with various F/Sn atomic ratios after annealing at 500 °C. The diffraction peaks were indexed as (1 1 0), (1 0 1), (2 0 0), and (2 1 1) of the cassiterite SnO₂ crystalline phase (JCPDS 70-4177). Similar diffraction patterns were observed by the incorporation of SnF₂ as a fluorine dopant. With increasing F/Sn atomic ratio, the diffraction pattern intensity gradually increased. Normally, the ionic radius of F[−] (1.33 Å) is close to that of O^{2−} (1.32 Å), so the doping process can take place easily, and the crystallinity of the films is not greatly affected [8]. The slight increase in the diffraction intensity with increasing F-content might be due to an increase in the thickness of FTO thin films. With increasing F/Sn atomic ratio, the thickness of FTO thin film was found to increase from 962 nm to 2.3 μ m by SEM. This thickness increase with increasing F/Sn ratio was due to the use of a fixed molarity of 0.3 M. That is, the absolute amount of Sn increased in the coating solution with increasing F/Sn ratio because the molecular weight of SnF₂ (156.71 g/mole) was smaller than that of SnCl₄·5H₂O (350.58 g/mole).

The electrical properties of SnO₂ thin films with various F/Sn atomic ratios were investigated by Hall Effect measurements,

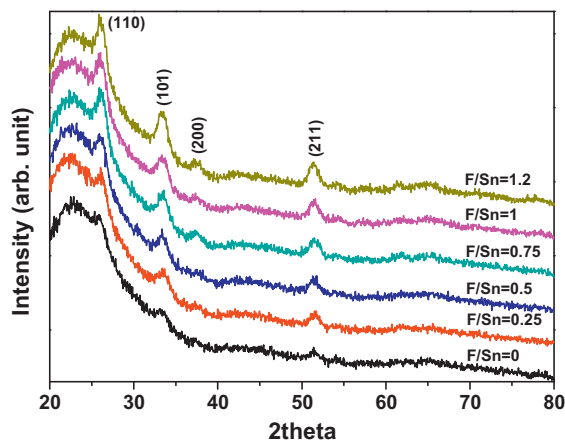


Fig. 1. XRD patterns of pure SnO₂ and F-doped SnO₂ thin films annealed at 500 °C with various F/Sn atomic ratios.

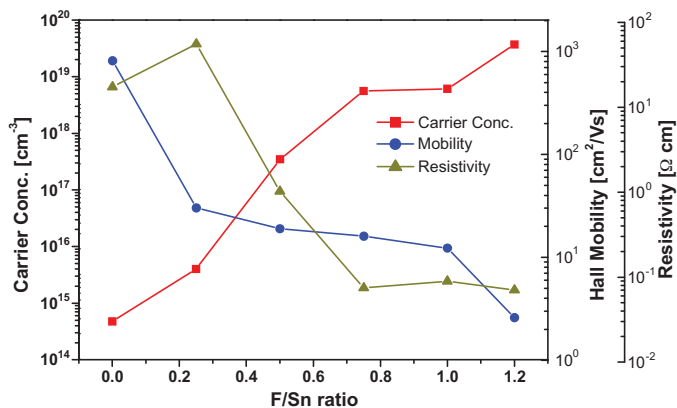


Fig. 2. Carrier concentration (■), mobility (●), resistivity (▲) of pure SnO₂ and F-doped SnO₂ thin films annealed at 500 °C with various F/Sn atomic ratios.

and the results are given in Fig. 2. The values confirm that carrier concentration, mobility, and resistivity were affected by the F/Sn atomic ratio. Carrier concentration and mobility of SnO₂ thin films were $4.757 \times 10^{14} \text{ cm}^{-3}$ and $812.7 \text{ cm}^2/\text{Vs}$, respectively. The carrier concentration increased with increasing F/Sn ratio. Fluorine doping generated free electrons by F-substitution into O sites. Mobility decreased due to increased electron scattering by excess free electrons and ionized impurities [9]. Variation in the resistivity is proportional to the carrier concentration and mobility, and the resistivity of FTO thin films decreased with increasing F/Sn atomic ratio. The carrier concentration and mobility of FTO thin films with F/Sn atomic ratio of 0.75 were $5.599 \times 10^{18} \text{ cm}^{-3}$ and $16.1 \text{ cm}^2/\text{Vs}$, respectively. The resistivity of SnO₂ thin films increased above an F/Sn ratio of 0.75 due to the influence of decreased electron mobility.

Fig. 3 shows UV–Vis transmittance spectra of SnO₂ thin films with various F/Sn atomic ratios. The transmittance of SnO₂ films slightly decreased in the visible light region by incorporation of fluorine dopant. The values of average transmittance in the visible region for F/Sn atomic ratios from 0 to 1.2 were 92.6, 91.0, 90.7, 88.2, 90.0, and 89.7% with increasing F/Sn ratio. A slight decrease in the optical transmittance with F/Sn ratio could be attributed to an increase in the film thickness and excess free electrons in the films [10].

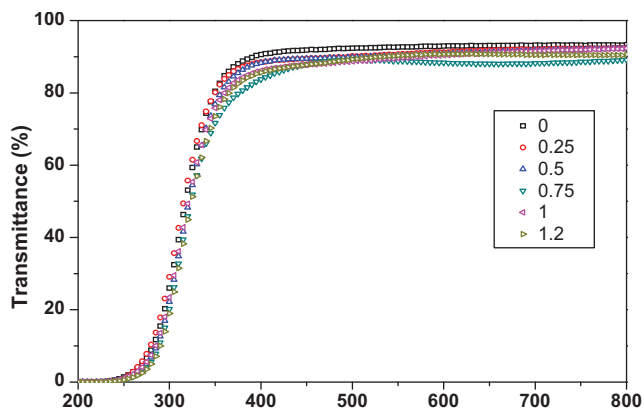


Fig. 3. Optical transmittance of pure SnO₂ and F-doped SnO₂ thin films annealed at 500 °C with various F/Sn atomic ratios.

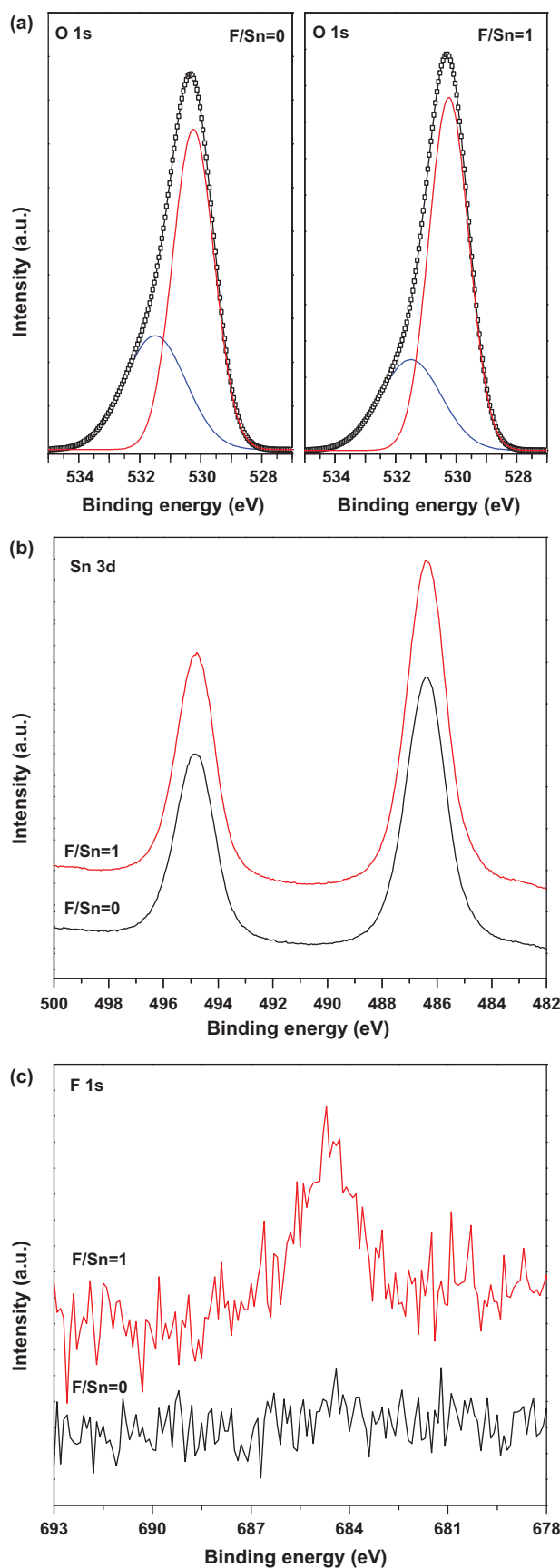


Fig. 4. XPS core level spectra of (a) O 1s, (b) Sn 3d, and (c) F 1s at the surface of pure SnO₂ and F-doped SnO₂ films with a F/Sn atomic ratio of 1 after annealing at 500 °C for 1 h.

Table 1

The atomic percentage of elements in the pure SnO₂ and F-doped SnO₂ thin films with a F/Sn atomic ratio of 1 after annealing at 500 °C for 1 h.

	C (%)	F (%)	O (%)	Sn (%)
Pure SnO ₂	14.23	–	65.01	20.76
F-doped SnO ₂	14.49	1.06	64.01	20.44

The electrical bonding states of pure SnO₂ and FTO thin films were analyzed using XPS, and the results are given in Fig. 4, which shows O 1s, Sn 3d, and F 1s core level spectra of pure SnO₂ and FTO thin films of a F/Sn atomic ratio of 1. The binding energies were corrected using the referencing C 1s peak at 284.5 eV. In Fig. 4(a), O 1s peaks of pure SnO₂ and FTO thin films were fitted, and the fitted binding energies were located at 530.24 eV and 531.5 eV, respectively. The peak binding energy around 530.24 eV is attributed to oxygen in Sn–O–Sn bonds. The other peak, positioned at 531.5 eV, is ascribed to surface hydroxyl groups –OH [11]. The atomic ratio of O/Sn of pure SnO₂ and FTO thin films except –OH bonds were 1.16 and 1.21, respectively. Due to the highly hydrophobic nature of fluorine, surface –OH groups were minimized with FTO, so the apparent surface composition of O/Sn for FTO was found to be larger than that of pure SnO₂. As shown in Fig. 4(c), the F 1s peak of the FTO thin film was observed at 684.7 eV. The atomic percentage of fluorine was 1.06 at% and the F/Sn atomic ratio was 0.05. The atomic percentage of elements in the SnO₂ films is summarized in Table 1. These values were calculated from core level spectra by using atomic sensitivity factors [12]. The fluorine content on the films was very low because fluorine vaporized from the films during the drying and annealing process [13].

The possibility of direct-patterning of FTO thin films was examined by removing the area unexposed to UV using a methanol. An optical micrograph in Fig. 5 contains a relatively dark area (green-reddish) corresponding to the FTO thin film and a bright area (bluish area) corresponding to the glass substrate. As shown at the edge of the centered pattern,

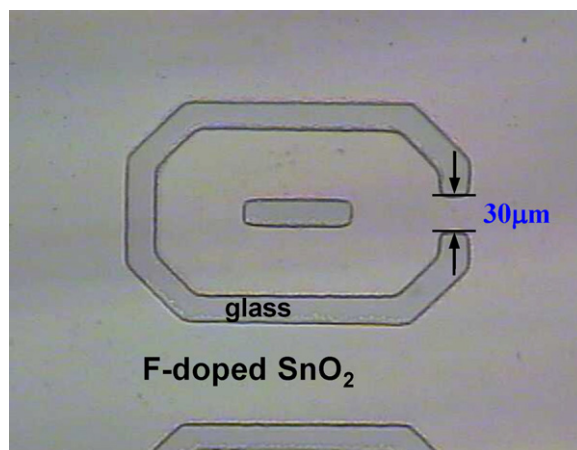


Fig. 5. Optical image of direct-patterned F-doped SnO₂ thin film after drying at 150 °C for 10 min.

micron-scaled patterning was successfully obtained by direct-patterning using photochemical solution deposition.

4. Conclusions

The crystallinity of the SnO_2 films was almost unaffected by the incorporation of fluorine dopant. With increasing incorporation content of fluorine in the SnO_2 film, the optical transmittance of the films slightly decreased and thickness increased. However, the resistivity of the FTO thin films was lower compared to pure SnO_2 film because the carrier concentration was increased due to free electron generation by fluorine substitution into O sites. Fluorine doping enhanced the electrical properties of direct-patternable SnO_2 thin films without significant degradation in the structural and optical properties. With direct-patterning of FTO thin films using PSD, a line-width of 30 μm was successfully performed without photoresists or dry etching.

Acknowledgements

This work was supported by the Korea Research Foundation Grant funded by the Korean Government (MOEHRD, Basic Research Promotion Fund) (KRF-2008-313-D00592). Experiments at PLS were supported in part by MEST and POSTECH.

References

- [1] Y. Sato, R. Tokumaru, E. Nishimura, P.K. Song, Y. Shigesato, K. Utsumi, H. Iigusa, Structural, electrical, and optical properties of transparent conductive In_2O_3 – SnO_2 films, *Journal of Vacuum Science and Technology A* 23 (2005) 1167–1172.
- [2] H. Kim, J.S. Horowitz, W.H. Kim, A.J. Mäkinen, Z.H. Kafafi, D.B. Chrisey, Doped ZnO thin films as anode materials for organic light-emitting diodes, *Thin Solid Films* 420–421 (2002) 539–543.
- [3] V.V. Simakov, O.V. Yakusheva, A.I. Grebennikov, V.V. Kisin, Current–voltage characteristics of thin-film gas sensor structures based on tin dioxide, *Technical Physics Letters* 31 (2005) 339–340.
- [4] M. Gao, R.H. Hill, High efficiency photoresist-free lithography of UO_3 patterns from amorphous films of uranyl complexes, *Journal of Materials Research* 13 (1998) 1379–1389.
- [5] E. Elangovan, K. Ramamurthi, Studies on micro-structural and electrical properties of spray-deposited fluorine-doped tin oxide thin films from low-cost precursor, *Thin Solid Films* 476 (2005) 231–236.
- [6] G.C. Morris, A.E. McElnea, Fluorine doped tin oxide films from spray pyrolysis of stannous fluoride solutions, *Applied Surface Science* 92 (1996) 167–170.
- [7] E.M. Levin, C.R. Robbins, H.F. McMurdie, *Phase Diagrams for Ceramists*, The American Ceramic Society, Columbus, 1981.
- [8] H. Kim, G.P. Kushto, R.C.Y. Auyeung, A. Piqué, Optimization of F-doped SnO_2 electrodes for organic photovoltaic devices, *Applied Physics A* 93 (2008) 521–526.
- [9] H.C. Lee, Electron scattering mechanism in indium–tin-oxide thin films prepared at the various process conditions, *Applied Surface Science* 252 (2006) 3428–3435.
- [10] P. Hertel, J. Appel, Light scattering on free electrons in semiconductors in the presence of electron-relaxation processes, *Physical Review B* 26 (1982) 5730–5742.
- [11] J.M. Themlin, M. Chtaïb, L. Henrard, P. Lambin, J. Darville, J.M. Gilles, Characterization of tin oxides by X-ray-photoemission spectroscopy, *Physical Review B* 46 (1992) 2460–2466.
- [12] J. Chastain, *Handbook of X-ray Photoelectron Spectroscopy*, Perkin-Elmer Corporation Physical Electronics Division, MN, 1992.
- [13] W.H. Claussen, The vapor pressure of fluorine, *Journal of the American Chemical Society* 56 (1934) 614–615.